

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) An adhesive material, for connecting a protuberant electrode of an electronic component to a terminal electrode of a circuit board for carrying ~~said the~~ electronic component, the adhesive material ~~containing~~ comprising at least one curable resin and ~~inorganic-silica~~ particles, wherein:

~~_____ as to the inorganic-silica particles, their~~ _____ have a specific surface area S (m^2/g) ~~satisfies-satisfying~~ Equation (1) below;

$$\text{_____} \quad 11 < S \leq 17 \quad \text{_____} \quad (1)$$

~~_____ their the silica particles have a mean particle size D_1 (μm) and maximum particle size D_2 (μm) respectively-satisfying~~ Equations (2) and (3) below, respectively,

$$\text{_____} \quad 11 < S \leq 17 \quad \text{_____} \quad (1)$$

$$D_1 \leq 5 \quad (2)$$

$$D_2 \leq 0.5 (h_1 + h_2) \quad (3)$$

~~_____~~ wherein h_1 represents the height of the protuberant electrode in the electronic component, and h_2 represents the height of the terminal electrode in the circuit board,

the content of ~~said inorganic~~ the silica particles is ~~10 to 60 vol%~~ 35 to 60 vol%,
and

~~wherein~~ the mean particle size D_1 of the ~~inorganic-silica~~ particles further satisfies the Equation (4) below.

$$0.1(h_1 + h_2) \geq D_1 \quad (4)$$

2-3. (Cancelled)

4. (Previously Presented) The adhesive material according to Claim 1, further containing conductive particles having a mean particle size of 0.5 to 8.0 μm .

5. (Previously Presented) The adhesive material according to Claim 1, wherein the adhesive material has a coefficient of moisture absorption in a 85% RH, 85°C atmosphere is 1.5 wt % or less.

6. (Previously Presented) The adhesive material according to Claim 1, wherein the electronic component is a semiconductor element.

7. (Cancelled)